

## Overview

Axiom Connectivity Digital Return SFPs are designed for superior flexibility and adaptability. By integrating numerous technical innovations, this Digital Return SFP Series ensures prolonged support for evolving network architectures.

## 1. Features

- Up to 2.5Gb/s
- Un Cooled DFB-LD
- SFP LC/UPC Receptacle(9/125um, SMF)
- Compliant with SFP(Small Form Factor Pluggable) MSA
- Digital Diagnostic Monitoring compliant
- Supports Serial ID functionality
- Class 1 Laser Safety products
- Single +3.3 V power supply with Hot-pluggable Interface
- ROHS compliant

## 2. Applications

- Digital repeater and Base station
- CPRI/OBSAI Line
- Fiber Channel

## 3. Regulatory Compliance

Items	Standard	Performance
<b>Electrostatic Discharge (ESD)</b>	IEC 61000-4-2	Class 1
<b>Electromagnetic Interference (EMI)</b>	FCC Part 15 Class B	Compliant with standards(FCC)
<b>Electromagnetic Compatibility (EMC)</b>	Directive 89/336/EEC	Compliant with standards(CE)
<b>Laser Eye Safety</b>	FDA 21CFR 1040.10 and 1040.11 EN (IEC) 60825-1,2	Class I laser product.
<b>RoHS</b>	Directive 2011/65/EU	Compliant with RoHS

## 4. Absolute Maximum Ratings

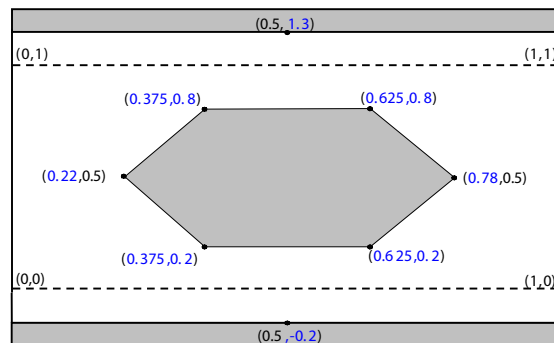
Parameters	Symbol	Ratings	Units	Conditions
Storage Temperature	T <sub>stg</sub>	-40 ~ +85	°C	-
Power Supply Voltage	V <sub>CC</sub>	< +4.0	V	-
Ambient Humidity	H <sub>op</sub>	5 ~ 95	%	w/o dew

### 5. Operating conditions

Parameters	Symbol	Values				Conditions
		Min.	Typ.	Max.	Units	
Power supply voltage	V <sub>CC</sub>	+3.135	+3.30	+3.465	V	-
Power supply current	I <sub>CC</sub>	-	-	500	mA	-
Power Supply Noise Rejection	PSNR	-	-	100	mV <sub>p-p</sub>	from 10Hz to 10MHz
Operating Temperature	T <sub>a</sub>	-40				Case, with Airflow
	T <sub>c</sub>	-	-	+85	°C	

### 6. Optical Characteristics

Parameters	Symbol	Values				Conditions
		Min.	Typ.	Max.	Units	
<b>Transmitter</b>						
Optical Transmit Power	P <sub>f</sub>	0	-	+5.0	dBm	-
Transmitter Disable(Off) Power	P <sub>off</sub>	-	-	-35	dBm	@Tx_Disable is High
Peak Wavelength	λ <sub>p</sub>	λ <sub>c</sub> -6.5	1491 1511	λ <sub>c</sub> +6.5	nm	DFB -LD,
Side Mode Suppression Ratio	SMSR	30	-	-	dB	-
Spectral Width	Δλ	-	-	1.0	nm	@ -20 dB
Extinction Ratio	ER	7.0	-	-	dB	@2.5Gb/s, PRBS 2 <sup>23</sup> -1
Eye pattern Mask	02xGbEthernet					



**Figure 1.** Mask of eye diagram for optical output (filtered)

**7. Electrical Characteristics**

Parameters		Symbol	Values				Conditions
			Min.	Typ.	Max.	Units	
<b>Transmitter</b>							
Data Rate		$DR_T$	-	2.5	-	Gb/s	
Differential Input Voltage		$V_{INpp}$	180	-	800	mV	-
Differential Input Impedance		$Z_{IN}$	90	100	110	ohm	-
Tx_Disable	Input_Low	$V_{IL}$	0	-	0.8	V	LVTTTL, Normal at Low, High is Shutdown( $P_{off}$ )
	Input_High	$V_{IH}$	2.0	-	3.465	V	
	Assert Time	$t_{OFF}$	-	-	10	us	High
	Negate Time	$t_{ON}$	-	-	1	ms	Low
Tx fault reset		$t_{reset}$	10	-	-	Us	High
Time to Initialize		$t_{start\_up}$	-	-	300	ms	-
Tx_Fault	Output_Low	$V_{FOL}$	0	-	0.8	V	LVTTTL, Low is Normal
	Output_High	$V_{FOH}$	2.0	-	$V_{CC}+0.3$	V	

### 8. Recommended Circuit Schematic

- Tx\_Disable : Transmitter Disable, logic high, 4.7k to 10kohm pull up to Vcc on SFP
- Tx\_Fault : Transmitter Fault, logic high, 4.7k to 10kohm pull up to Vcc on Host

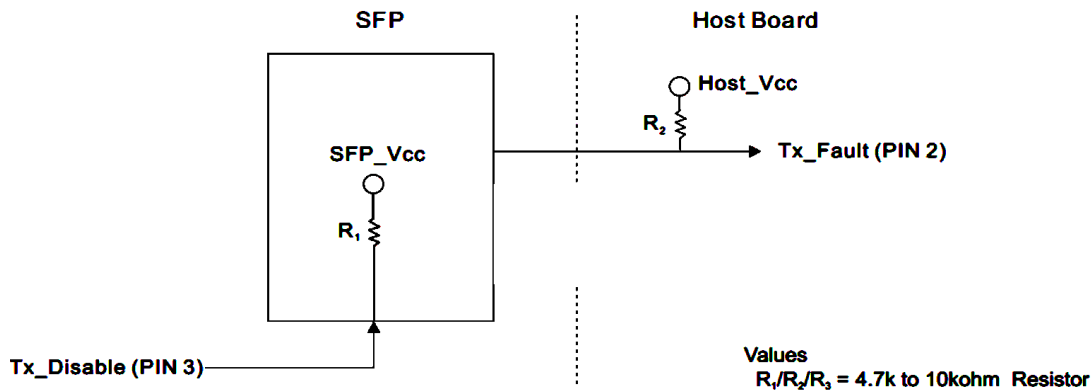


Figure 2. Signal Definitions

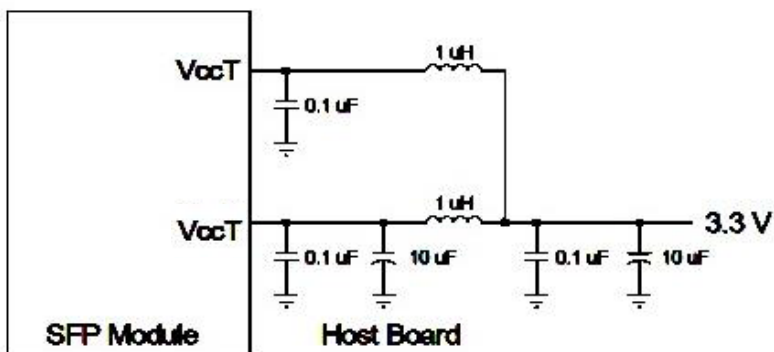


Figure 3. Power Coupling

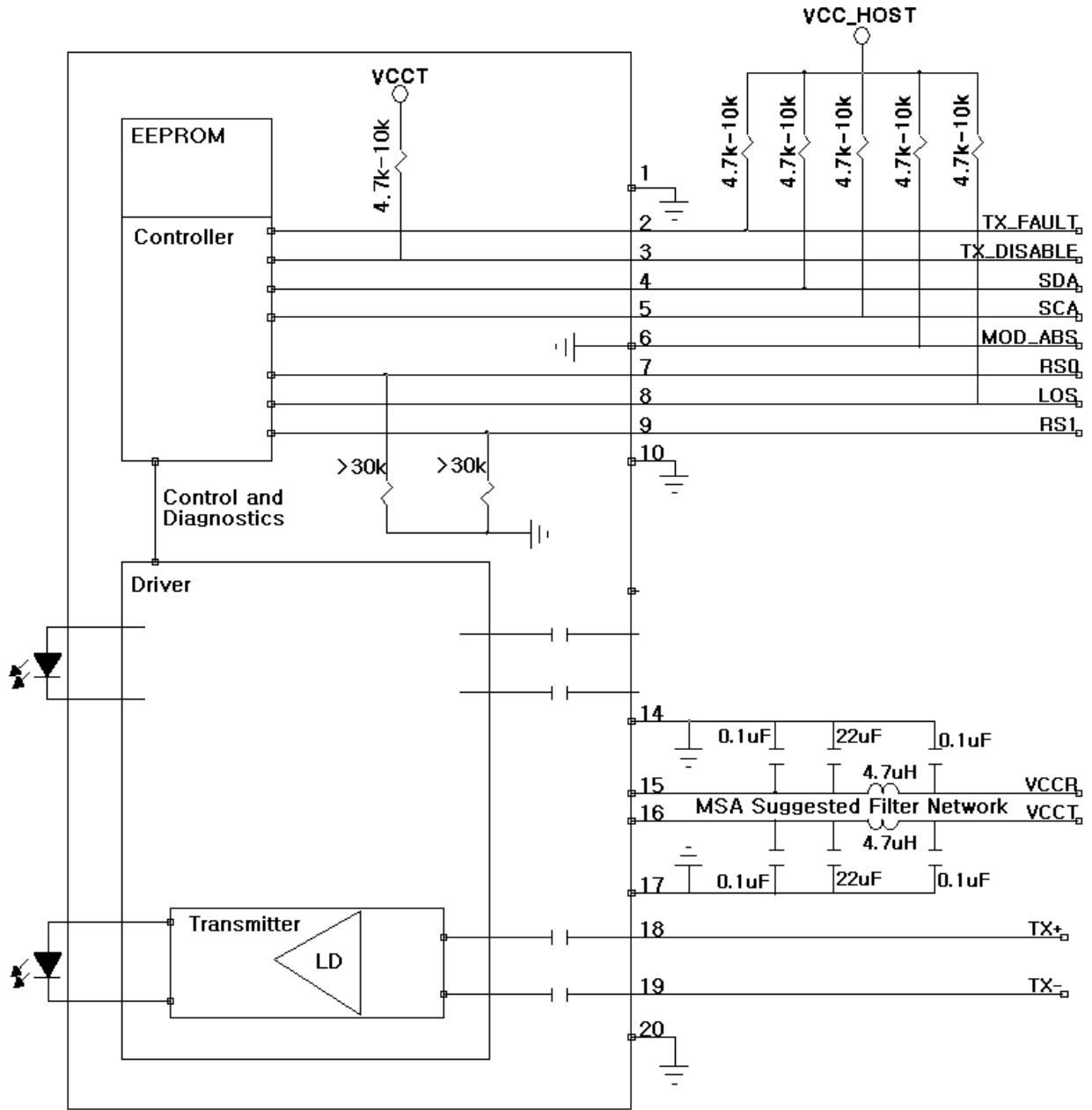
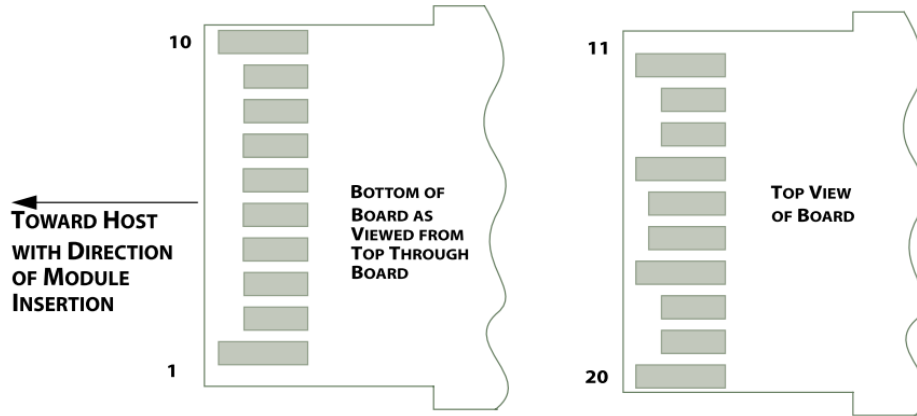
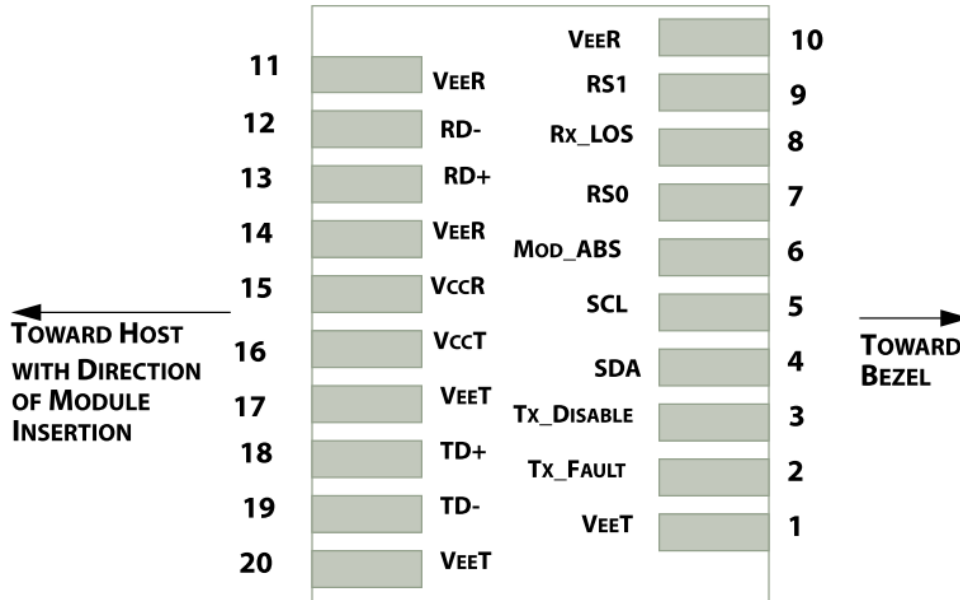


Figure 4. Example SFP Host Board Schematic

**9. Pin Information**



**Figure 5-1.** SFP+ Transceiver Electrical Pad Layout



**Figure 5-2.** 20-pin Host PCB SFP+ pad assignment top view

Pin No.	Symbol	Descriptions	Sequence
Pin 1	TGND (VeeT)	Ground	1
Pin 2	Tx_Fault	Status Out	3
Pin 3	Tx_Disable	Control In	3
Pin 4	MOD_DEF(2)	Input/Output(SDA, I <sup>2</sup> C data)	3
Pin 5	MOD_DEF(1)	Input/Output(SCL, I <sup>2</sup> C clock)	3
Pin 6	MOD_DEF(0)	Indicates that the module is present , Grounded internally	3
Pin 7	Rate Select	Rate Select In, Not used (Internally N.C)	3
Pin 8	RX_LOS	Status Out	3
Pin 9	RGND (VeeR)	Ground	3
Pin10	RGND (VeeR)	Ground	1
Pin 11	RGND (VeeR)	Ground	1
Pin 12	Rx_Data bar	Data Out Negative	3
Pin 13	Rx_Data	Data Out Positive	3
Pin 14	RGND (VeeR)	Ground	1
Pin 15	Rx_Vcc (VccR)	Power	2
Pin 16	Tx_Vcc (VccT)	Power	2
Pin 17	TGND (VeeT)	Ground	1
Pin 18	Tx_Data	Data In Positive	3
Pin 19	Tx_Data bar	Data In Negative	3
Pin 20	TGND(VeeT)	Ground	1

**10. 2-Wire Interface Electrical Specifications**

Parameters	Symbol	Min.	Max.	Units	Notes
Host 2 -Wire Vcc	V <sub>cch</sub>	3.14	3.46	V	Note 1
SCL and SDA	V <sub>OL</sub>	0.0	0.8	V	R <sub>P</sub> pulled to V <sub>ccT</sub> /R, Note 2
	V <sub>OH</sub>	V <sub>cch</sub> -0.5	V <sub>cch</sub> +0.3	V	
SCL and SDA	V <sub>IL</sub>	-0.3	V <sub>ccT</sub> *0.3	V	Note 3
	V <sub>IH</sub>	V <sub>ccT</sub> *0.7	V <sub>ccT</sub> +0.5	V	
Input Current on the SCL and SDA Contacts	I <sub>I</sub>	-10	10	μA	-
Capacitance on SCL and SDA contacts	C <sub>i</sub>	-	14	pF	Note 4
Total bus capacitance for SCL and SDA	C <sub>b</sub> <sup>[5]</sup>	-	100	pF	At 400kHz, 3.0k Ω R <sub>p</sub> , max At 100kHz, 8.0k Ω R <sub>p</sub> , max
		-	290	pF	At 400kHz, 1.1k Ω R <sub>p</sub> , max At 100kHz, 2.75k Ω R <sub>p</sub> , max

**Notes:**

1. The Host 2-wire Vcc is the voltage used for resistive pull ups for the 2 wire interface
2. R<sub>p</sub> is the pull up resistor. Active bus termination may be used by the host in place of a pull up resistor. Pull ups can be connected to any one of several power supplies, however the host board design shall ensure that no module contact has voltage exceeding module V<sub>ccT</sub>/R + 0.5 V nor requires the module to sink more than 3.0mA current.
3. These voltages are measured on the other side of the connector to the device under test.
4. C<sub>i</sub> is the capacitance looking into the module SCL and SDA contacts. 0
5. C<sub>b</sub> is the total bus capacitance on the SCL or SDA bus.



### 11. 2-Wire Timing Specifications

Parameters	Symbol	Min.	Max.	Units	Notes
Clock Frequency	$f_{SCL}$	0	400	kHz	Note 1
Clock Pulse Width Low	$t_{LOW}$	1.3	-	$\mu s$	-
Clock Pulse Width High	$t_{HIGH}$	0.6	-	$\mu s$	-
Stop to Start Time	$t_{BUF}$	20	-	$\mu s$	Note 2
Start Hold Time	$t_{HD,STA}$	0.6	-	$\mu s$	-
Start Set -up Time	$t_{SU,STA}$	0.6	-	$\mu s$	-
Data In Hold Time	$t_{HD,DAT}$	0	-	$\mu s$	-
Data In Set -up Time	$t_{SU,DAT}$	0.1	-	$\mu s$	-
Input Rise Time (100kHz)	$t_{R,100}$	-	1000	ns	Note 3
Input Rise Time (400kHz)	$t_{R,400}$	-	300	ns	Note 3
Input Fall Time (100kHz)	$t_{F,100}$	-	300	ns	Note 4
Input Fall Time (400kHz)	$t_{F,400}$	-	300	ns	Note 4
Stop Set -up Time	$t_{SU,STO}$	0.6	-	$\mu s$	-
Serial Interface Clock Holdoff "Clock Stretching "	$t_{\_clock\_hold}$	-	500	$\mu s$	Note 5

**Notes:**

1. Module shall operate with  $f_{SCL}$  up to 100 kHz without requiring clock stretching. The module may clock stretch with  $f_{SCL}$  greater than 100 kHz and up to 400 kHz.
2. Between STOP and START and between ACK and Re-START.
3. From  $(V_{IL,MAX} - 0.15)$  to  $(V_{IH,MIN} + 0.15)$
4. From  $(V_{IH,MIN} + 0.15)$  to  $(V_{IL,MAX} - 0.15)$
5. Maximum time the module may hold the SCL line low before continuing with a read or write operation.

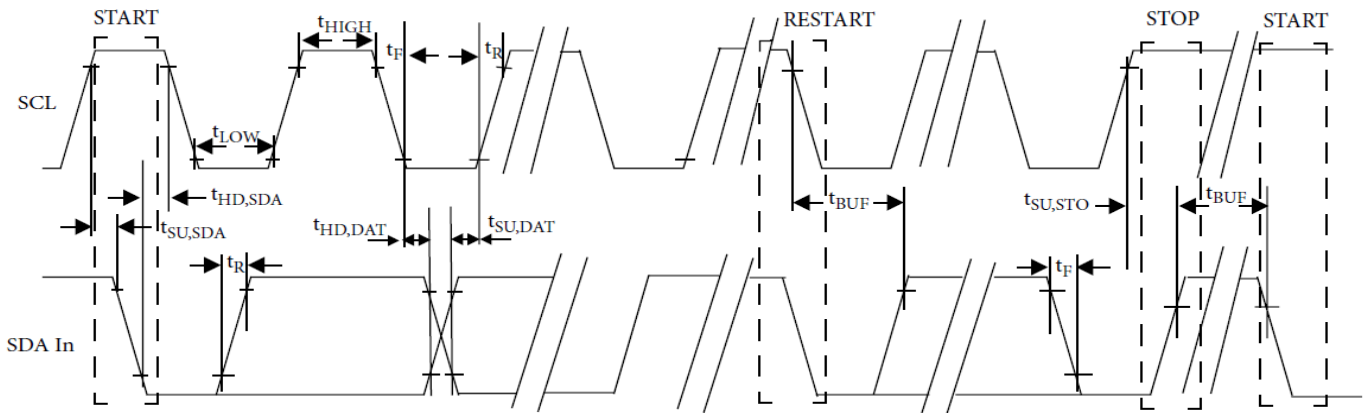


Figure 4. 2-Wire Bus Timing Diagram

**12. Package Description & Outline Diagram**

\* Unit: [mm]

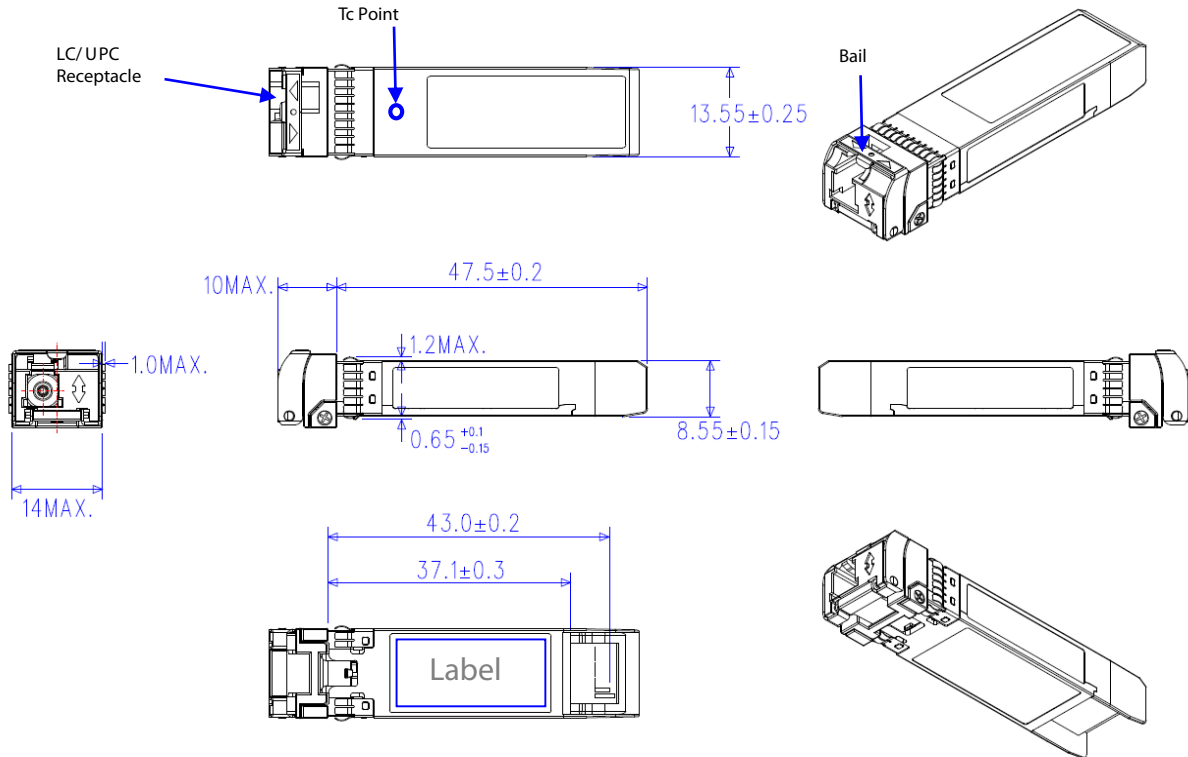


Figure 5. Package outline diagram and example

**\* Part number information**

Part No	Wavelength [nm]
AC-B-DR2XC80-l27-yy	1271
AC-B-DR2XC80-l29-yy	1291
AC-B-DR2XC80-l31-yy	1311
AC-B-DR2XC80-l33-yy	1331
AC-B-DR2XC80-l35-yy	1351
AC-B-DR2XC80-l37-yy	1371
AC-B-DR2XC80-l39-yy	1391
AC-B-DR2XC80-l41-yy	1411
AC-B-DR2XC80-l43-yy	1431
AC-B-DR2XC80-l45-yy	1451
AC-B-DR2XC80-l47-yy	1471
AC-B-DR2XC80-l49-yy	1491
AC-B-DR2XC80-l51-yy	1511
AC-B-DR2XC80-l53-yy	1531
AC-B-DR2XC80-l55-yy	1551
AC-B-DR2XC80-l57-yy	1571
AC-B-DR2XC80-l59-yy	1591
AC-B-DR2XC80-l61-yy	1611